



TERABOARD kick-off meeting

Pisa, December 15 -16, 2015

Agenda

Tuesday Dec 15

12:30 – 13:30 Lunch

13:30 – 13:45 Welcome and overview of the project planning and detailed planning for first period

13:45 – 15:15 Technical presentations

15:30 – 15:45 Coffee break

15:45 – 17:00 Technical presentations

20:00 Dinner at 'La Clessidra'

Wednesday Dec 16

9:00 – 10:30 Technical presentation and discussions

10:30 – 10:45 Coffee break

10:45 – 12:00 Administrative items: mailing lists, pre-financing, progress of CA

12:00 – 12:15 Recap – plan for next meetings

Tech Presentations & Discussion

Tuesday Dec 15

13:45 – 14:00 Requirements and specs (Ericsson)

14:00 – 15:30 First Part
Chip Design & Fabrication (IMEC - Si Photonics TRXs & laser integration, IMINDS - Electronic ICs, CNIT - Starboard & Connector, Alcatel – WDM Connector, CNR – Optical VIAs)

15:45 – 17:00 Second Part
Chip Design & Fabrication (IMEC - Si Photonics TRXs & laser integration, IMINDS - Electronic ICs, CNIT - Starboard & Connector, Alcatel – WDM Connector, CNR – Optical VIAs)

Wednesday Dec 16

9:00 – 10:00 Assembly & Packaging (ST, UPV, CNIT – Si Photonics chips on Staboard and connectors, Prototype)

10:00 – 10:30 Testing (CNIT – silica connectivity and prototype, IMEC, IMINDS – photonics, electronics, integrated photonics and electronics, IMEC – testing integrated laser)